Statement No.: EN/RMSC/PCFV/2025/04/008



Product Carbon Footprint Verification Statement

This statement is issued to:

HEJIAN TECHNOLOGY (SUZHOU) CO., LTD

Company Address: No.333, Xing Hua Street, Suzhou Industrial Park, Suzhou Area, China (Jiangsu) Pilot Free Trade Zone, P.R. China.

Factory Address: No.333, Xing Hua Street, Suzhou Industrial Park, Suzhou Area, China (Jiangsu) Pilot Free Trade Zone, P.R. China.

Submitted report for this verification is 8 inch wafer PCF report

Declared Unit / Functional Unit: Product Carbon Footprints of an 8 inch wafer from cradle to gate is 254.83 kg CO2e

The PCF report and supporting documents for above mentioned product has been provided by the company and reviewed by SGS as in accordance with ISO 14040:2006 Environmental management – Life Cycle Assessment – Principles and Framework, ISO 14044:2006 Environmental management – Life Cycle Assessment – Requirements and Guidelines, and refer to ISO 14067:2018 Greenhouse gases – Carbon footprint of products – Requirements and guidelines for quantification.

This verification statement shall be used to the above 8 inch wafer PCF report (report no.: PCFV/2025/04/008) as an integral explanation.

Signed by

Chris Chen

Issue Date: 19/05/2025 Green Product Service Voluntary Product Certification Centre

SGS-CSTC Standards Technical Services Co., Ltd. 16/F, Century Yu Hui Mansion, No. 73 Fucheng Road, Beijing, 100142, PRC t +86(0) 10 6845-6699 f +86(0) 10 6845-8121 www.sgs.com

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Indemnification and jurisdiction issues defined therein.

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SGS

Statement No.: EN/RMSC/PCFV/2025/04/008, continued

This PCF reasonable assurance statement also includes below contents:

Life Cycle Stage

Carbon Footprint (Unit: kg CO2 eq)

Raw Material Acquisition

82.36

Manufacture

172.47

Total

254.83

Product Description:

HeJian 8 inch wafer

System Boundary:

The Life cycle stages of from cradle to gate which included

raw material acquisition, transportation and manufacturing

processes.

Data Collection:

Data collected for this PCF calculation and reporting was

from 01/01/2024 to 12/31/2024.

Data Source:

Primary data was collected from raw material and manufacturing site of the product, secondary data was from 100-year global warming potentials defined by the Intergovernmental Panel on Climate Change (IPCC 2021, Table 7.SM.7), and life cycle database Ecoinvent 3.8.

Allocation:

Physical properties.

Cut-off Rules:

Cutoff in this study include:

Based on input/output share: for common material weight <1% product weight, the upstream production data for the material is ignored, but the total cutoffed product input

share does not exceed 5%.

Based on the weight of potential environmental impacts: estimate with similar inputs and exclude inputs/outputs

with less actual impacts.

PCF Report:

The PCF report was submitted by the listed company on 16/05/2025 and verified by SGS to its materially accuracy.

The data information of the verified product was

authentically revealed, and the quantifying, monitoring and reporting were in accordance with ISO 14067:2018, ISO 14040:2006 and ISO 14044:2006 standards requirements.

Signed by

Chris Chen

Issue Date: 19/05/2025 Green Product Service

Voluntary Product Certification Centre